F I G. 1

FIG. 2

FIG. 3A

FIG. 3B

(SECTIONAL VIEW TAKEN ALONG LINE A-A)

F I G. 4

16c

16b

16a

FIG. 5

ENLARGED VIEW OF PORTION B

F I G. 6

ENLARGED VIEW OF PORTION C
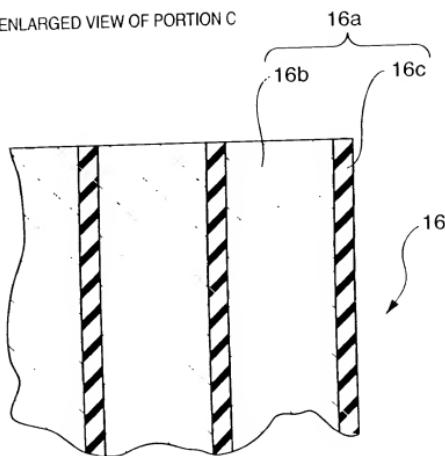
F I G. 7A
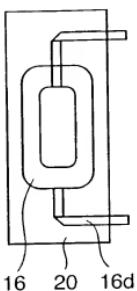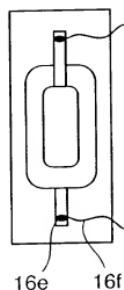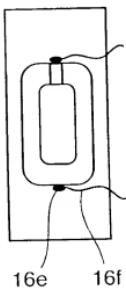


16　20　16d

F I G. 7B

16e　　16f

F I G. 7C

16e　　16f

F I G. 7D

16e　　16f

FIG. 8A

16   20

FIG. 8B

16e   16f

FIG. 8C

16e   16f

FIG. 8D

16e   16f

FIG. 9A

FIG. 9B

16h 16i 16g

16i 16h 16g

D ———————— D

16 16f 16e

16f 16e

FIG. 9C

16

16g 16g

16g

FIG. 10A

16j   16j   16

16g   16g   16g

FIG. 10B

16j   16j   16

FIG. 10C

16k   16k   16

16g   16k   16g   16k   16g
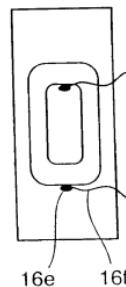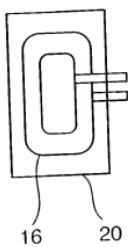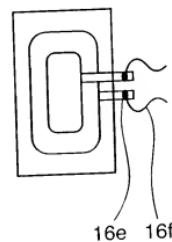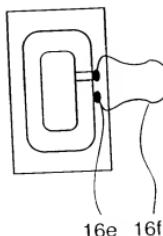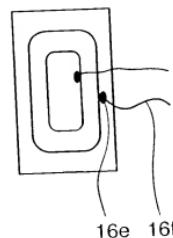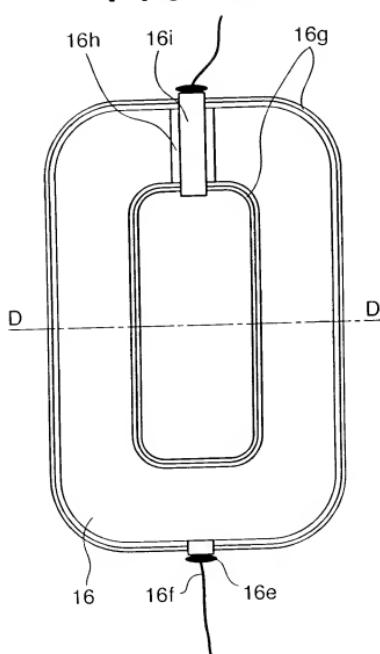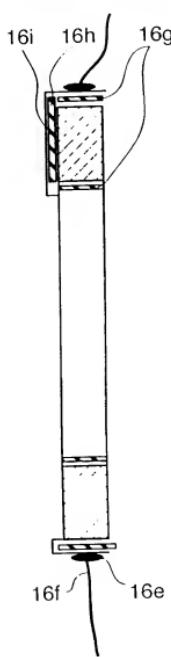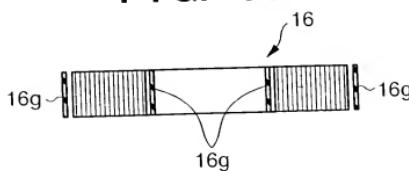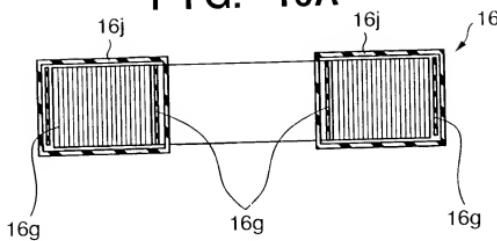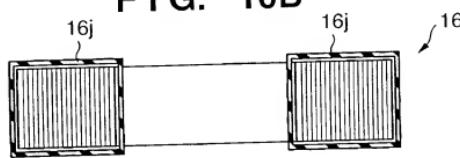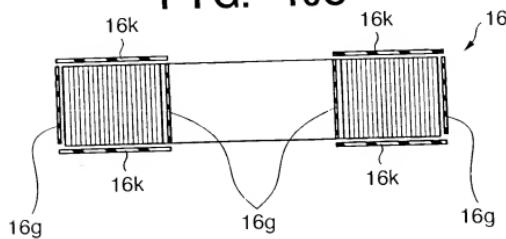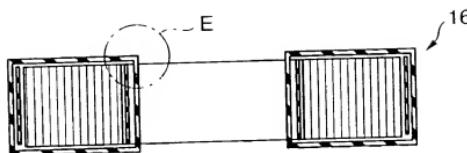
F I G. 11A

F I G. 11B

ENLARGED VIEW OF PORTION E

FIG. 12A

F

16
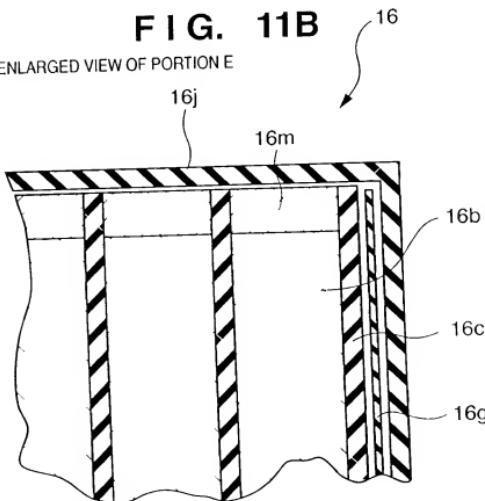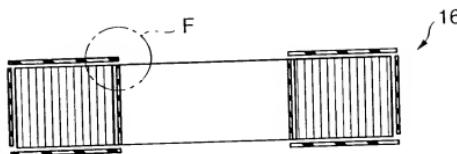
FIG. 12B

ENLARGED VIEW OF PORTION F

16k

16m

16

16b

16c

16g

FIG. 13A

16p
16n

FIG. 13B

16q
16r
16p   16n

INNER CIRCUMFERENTIAL
SURFACE α WINDING

FIG. 13C

16q
16s
16p   16n

INNER CIRCUMFERENTIAL
SURFACE BENDING / SHIFT WINDING

F I G. 14

F I G. 15A

20 (24, 26)

20a

16

F I G. 15B

20a

16

F I G. 16A

16c

16t

16a

F I G. 16B

16c

16b

16a

FIG. 17
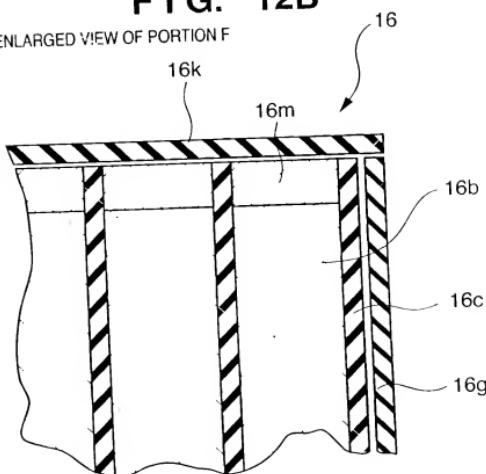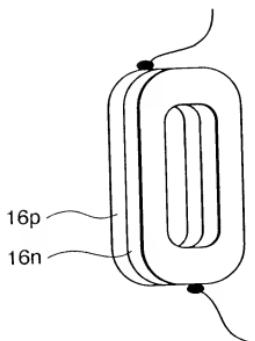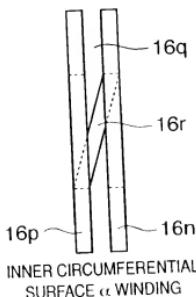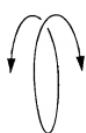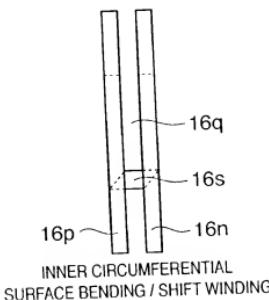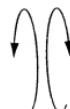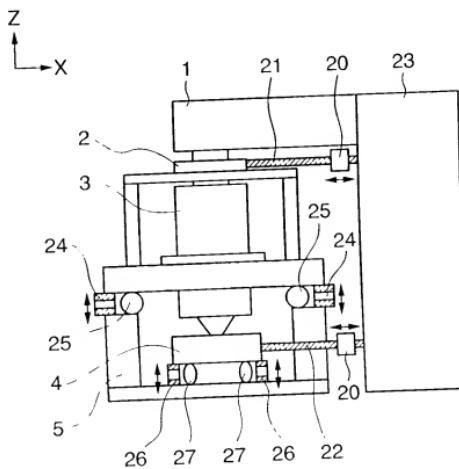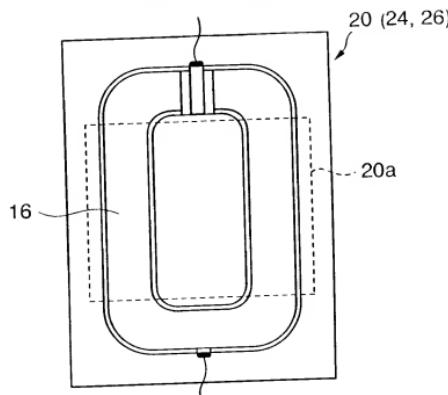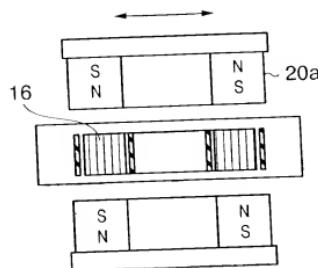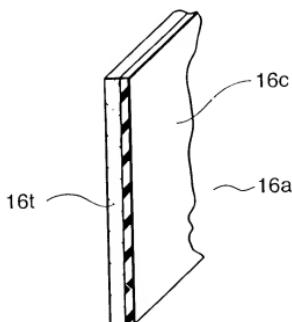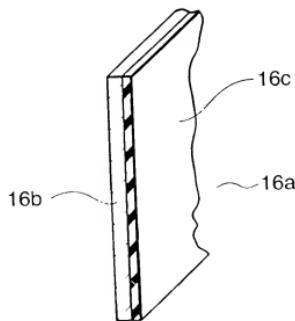
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└──────────────────┘                    └──────────────────┘
         │                                       │
         ▼                                       │
┌──────────────────┐                             │
│    FORM MASK     │─ STEP2                       │
└──────────────────┘                             │
         │                                       │
         └───────────────┬───────────────────────┘
                         ▼
              ┌──────────────────┐
              │  WAFER PROCESS   │─ STEP4
              │  (PRE-PROCESS)   │
              └──────────────────┘
                         │
                         ▼
              ┌──────────────────┐
              │    ASSEMBLY      │─ STEP5
              │  (POST-PROCESS)  │
              └──────────────────┘
                         │
                         ▼
              ┌──────────────────┐
              │    INSPECTION    │─ STEP6
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              │     SHIPPING     │─ STEP7
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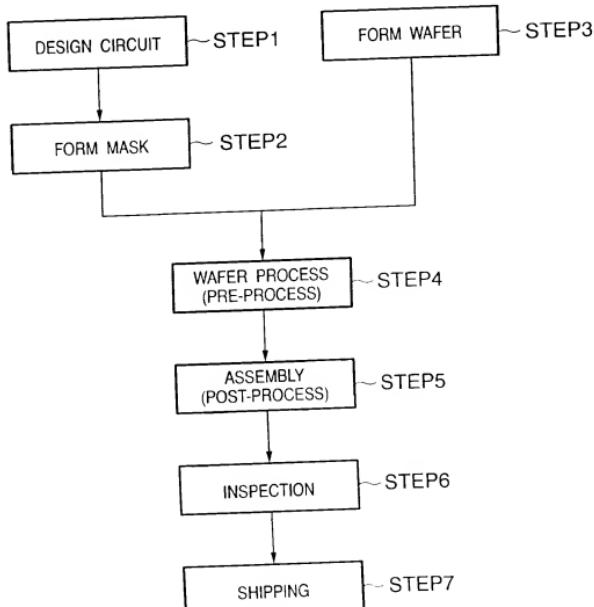
SEMICONDUCTOR DEVICE MANUFACTURING FLOW

FIG. 18

STEP11
OXIDATION

STEP12
CVD

STEP13
FORM ELECTRODE

STEP14
IMPLANT ION

STEP15
RESIST PROCESSING

STEP16
EXPOSURE

STEP17
DEVELOPING

STEP18
ETCHING

STEP19
REMOVE RESIST

REPEAT

WAFER PROCESS
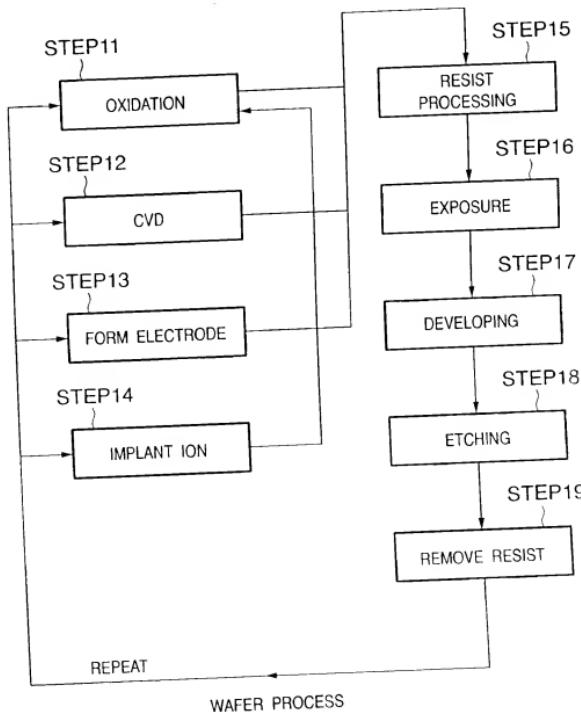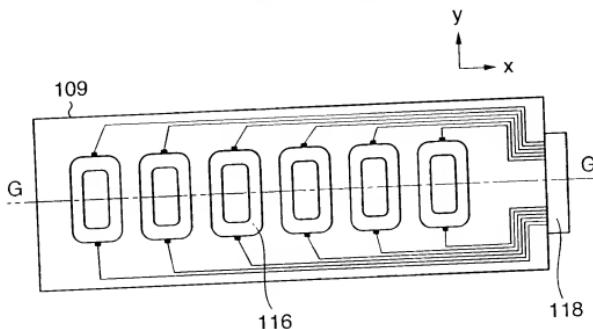
F I G. 19A

F I G. 19B
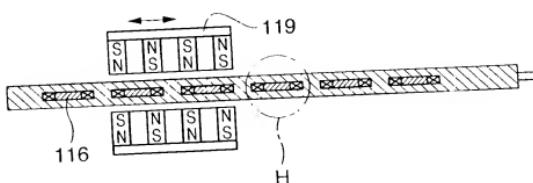
(SECTIONAL VIEW TAKEN ALONG LINE G-G)

F I G. 20

116b

116a

116c
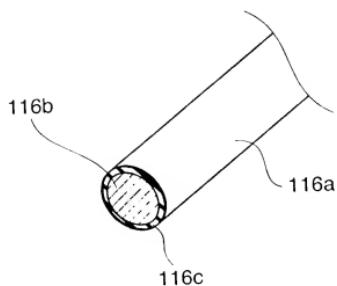
F I G. 21

ENLARGED VIEW OF PORTION H
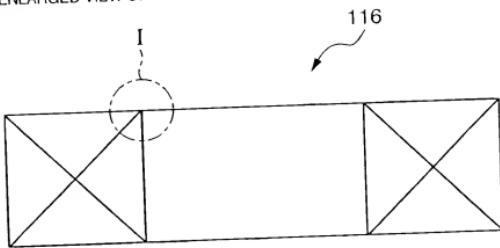
F I G. 22

ENLARGED VIEW OF PORTION I
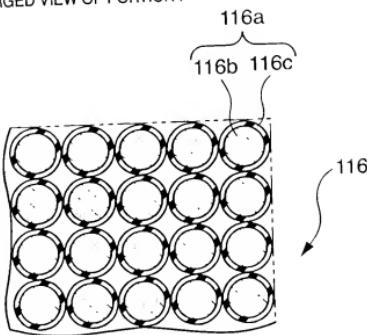
F I G. 23A
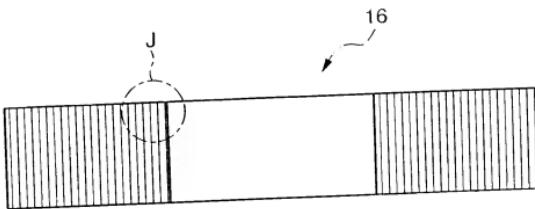
F I G. 23B

(ENLARGED VIEW OF PORTION J)

PROJECTION AT END OF
INSULATING BASE FILM

16a
16b   16c

16

FIG. 24A

24/33

16

PROJETION
AT END OF
INSULATING
BASE FILM

16b 16c

16a

28

FIG. 24B

29b 29c

PROJETION
AT END OF
INSULATING
BASE FILM

16b 16c

29a

FIG. 24C

29d

PROJETION
AT END OF
INSULATING
BASE FILM

16b

16c

FIG. 24D

29e

PROJETION
AT END OF
INSULATING
BASE FILM

16b 16c

F I G. 25A

K

16
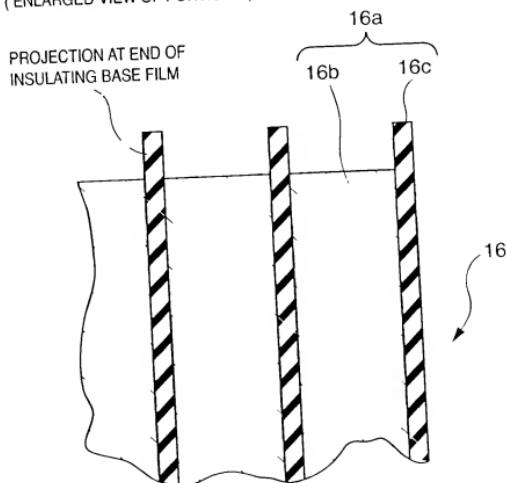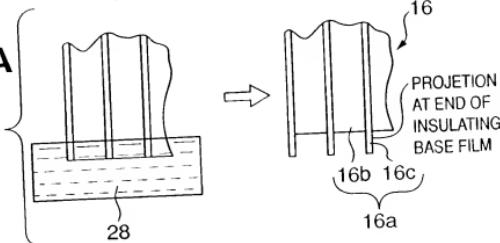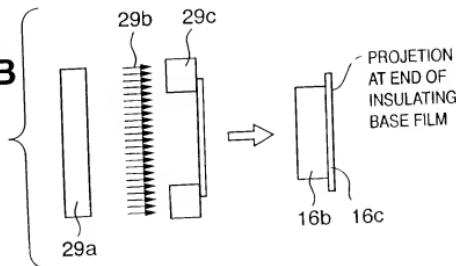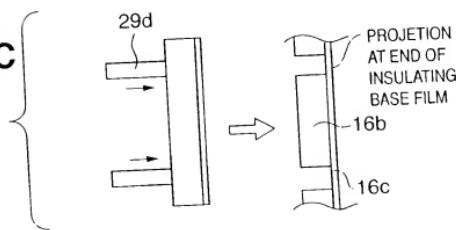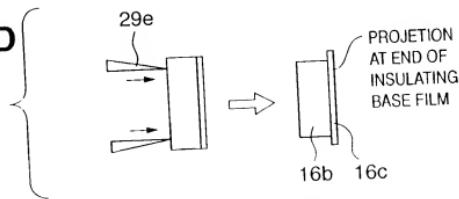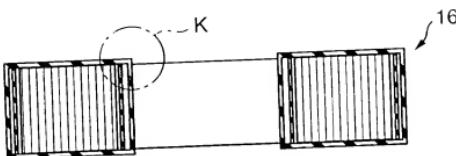
# F I G. 25B

(ENLARGED VIEW OF PORTION K)

16

16j

PROJETION AT END OF
INSULATING BASE FILM

16b

16c

16g

FIG. 26A

L
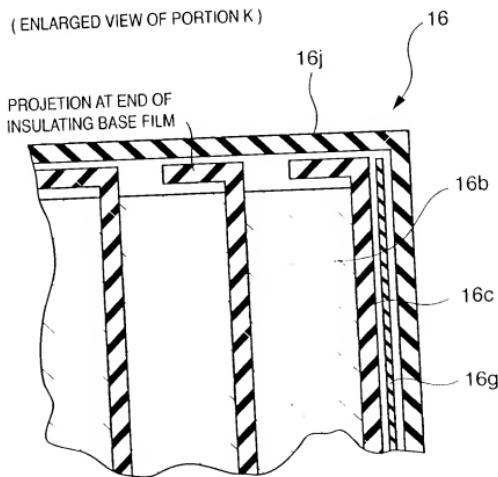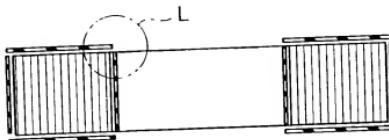
FIG. 26B

(ENLARGED VIEW OF PORTION L)

PROJETION AT END OF
INSULATING BASE FILM

16k

16

16b

16c

16g

FIG. 27A

16c

30a, 30b, 30c

16a

FIG. 27B

19

S	N	S	N
N	S	N	S

19a

16

S	N	S	N
N	S	N	S

FIG. 27C

16c

16b

16a

F I G. 28A

16c

30d

16a

F I G. 28B

30d

30f

16c

30e

F I G. 28C

30d

PROJETION
AT END OF
INSULATING
BASE FILM
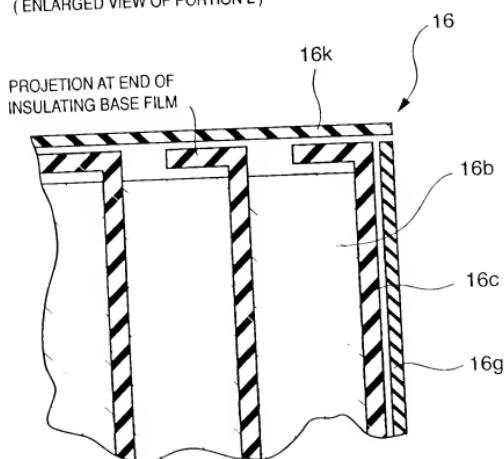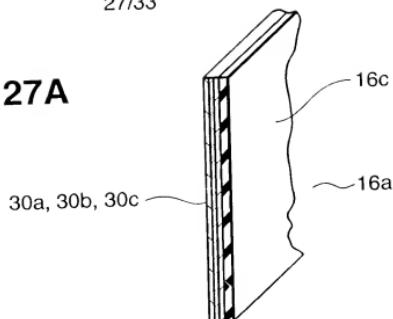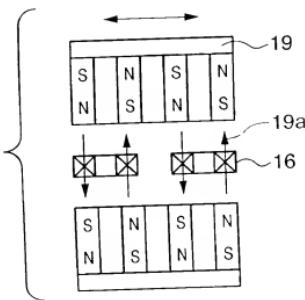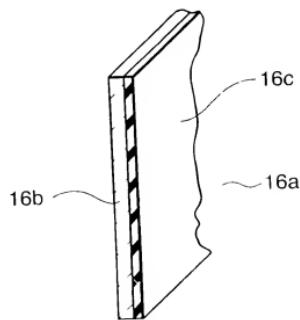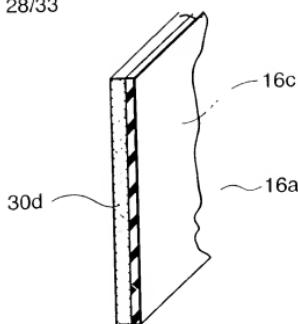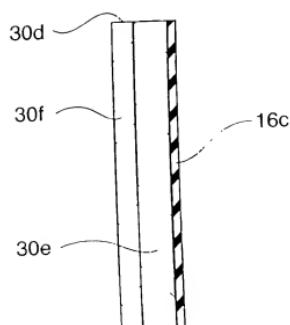
16c
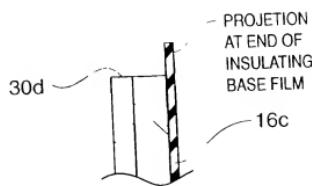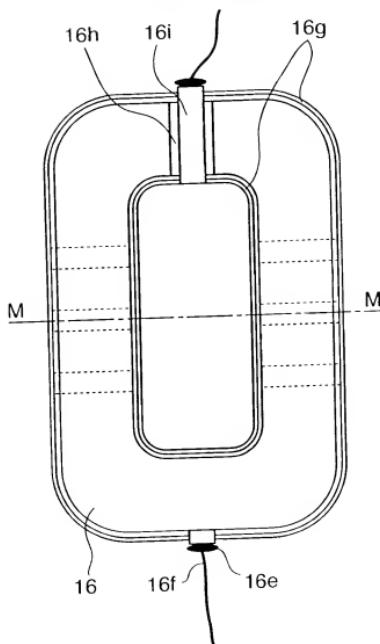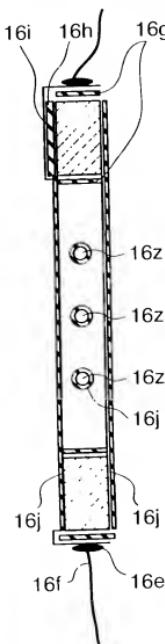
F I G. 29A

F I G. 29B

# F I G. 29C
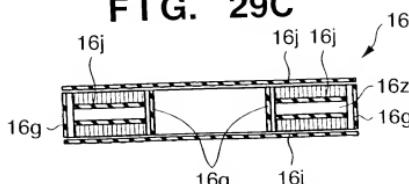

(SECTIONAL VIEW TAKEN ALONG LINE M-M)

F I G. 30

F I G. 31

FIG. 32

FIG. 33
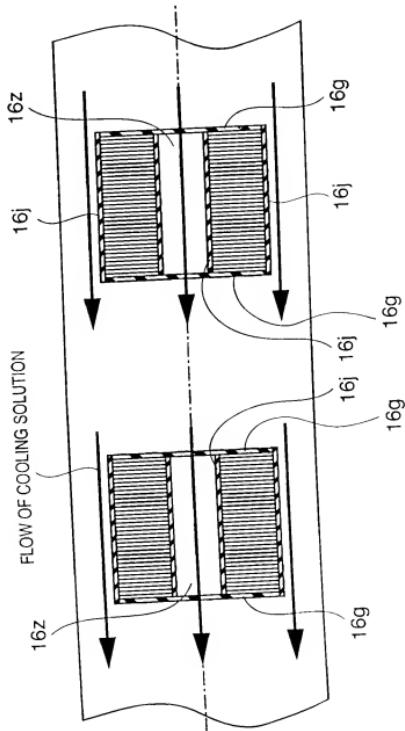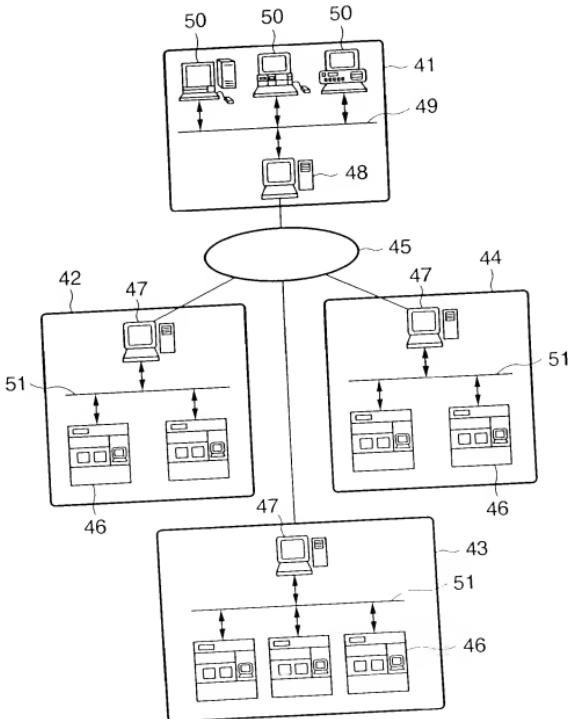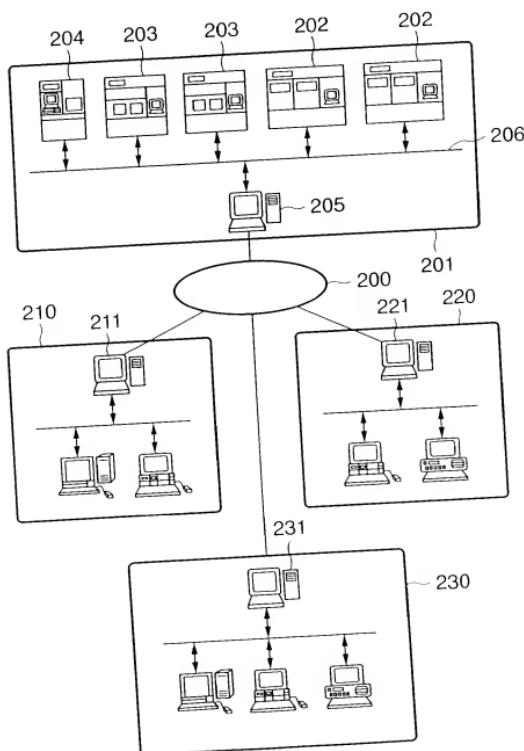
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TROUBLE DB INPUT WINDOW

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TYPE OF APPARATUS [* * * * * * * * * *] ~ 401
OBJECT [OPERATION ERROR (START-UP ERROR)] ~ 403
DEVICE S/N [465NS4580001] ~ 402
DEGREE OF URGENCY [D] ~ 405

SYMPTOM [LED KEEPS FLICKERING AFTER POWER ON] ~ 406

REMEDY [POWER ON AGAIN (PRESS RED BUTTON IN ACTIVATION)] ~ 407

PROGRESS [INTERIM HAS BEEN DONE] ~ 408

[SEND] [RESET]   410   411   412
LINK TO RESULT LIST DATABASE   SOFTWARE LIBRARY   OPERATION GUIDE